



I3S 2019
7th
International
Symposium on
Sensor
Science

I3S 2019
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<https://i3s2019napoli.sciforum.net>

Napoli, 4 March 2019

Letter of Support to Attend the 7th International Symposium on Sensor Science (I3S 2019)

To whom it may concern,

We would like to confirm that the following person will be attending the 7th International Symposium on Sensor Science (I3S 2019), which will take place at Napoli, Italy, on 9 – 11 May 2019.

Mr. Rongshan Wei

We would also like to confirm that the following submission has been accepted as poster presentation in I3S 2019:

Submission ID: sciforum-023193

Title: Design of Double Three-Contact Vertical Hall Device Based on Conformal Mapping Technology

Authors: Rongshan Wei *, Yuxuan Du

Conference: 7th International Symposium on Sensor Science

Section: Physical Sensors

Mr. Rongshan Wei will make his own flight and accommodation arrangements and is responsible for his own travel costs related to this conference.

We can confirm that Mr. Rongshan Wei has completed the payment of the registration fees of this event (500€).

Detail on the conference and scientific program can be found online at: <https://i3s2019napoli.sciforum.net>

We look forward to Mr. Rongshan Wei's attendance to the symposium.

Yours sincerely,

Prof. Dr. Nunzio Cennamo
Department of Engineering
University of Campania Luigi Vanvitelli
Aversa, Italy
Chair of I3S 2019



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